



SSC8LA14GTL

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
100V	$\pm 20V$	1.2m Ω @10V	403A

➤ Description

The SSC8LA14GTL is N-Channel enhancement mode MOSFET. Uses SGT Technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in DC - DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

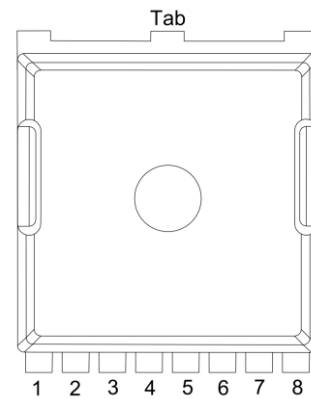
➤ Applications

- Inverter
- DC-DC Converter
- Half and Full Bridge Topology
- Motor Drive Control

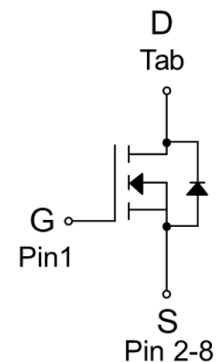
➤ Ordering Information

Device	Package	Shipping
SSC8LA14GL	TOLL	2000/Reel

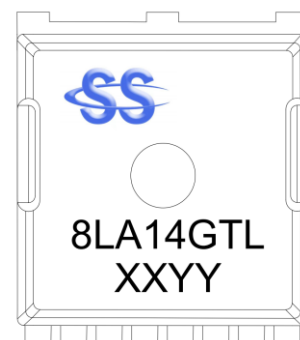
➤ Pin configuration



TOLL (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DSS}	Drain-to-Source Voltage		100	V
V_{GSS}	Gate-to-Source Voltage		± 20	V
I_D	Continuous Drain Current ^b	$T_C = 25^{\circ}\text{C}$	403	A
		$T_C = 100^{\circ}\text{C}$	224	A
I_{DM}	Pulsed Drain Current ^b		1613	A
I_{DSM}	Continuous Drain Current ^a	$T_A = 25^{\circ}\text{C}$	36	A
		$T_A = 70^{\circ}\text{C}$	26	A
P_D	Power Dissipation ^c	$T_C = 25^{\circ}\text{C}$	313	W
		$T_C = 100^{\circ}\text{C}$	125	W
P_{DSM}	Power Dissipation ^a	$T_A = 25^{\circ}\text{C}$	2.5	W
		$T_A = 70^{\circ}\text{C}$	1.6	W
I_{AS}	Avalanche Current ^b $L = 0.5\text{mH}$		72	A
E_{AS}	Avalanche Energy ^b $L = 0.5\text{mH}$		1296	mJ
T_J	Operation junction temperature		-55 to 150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55 to 150	$^{\circ}\text{C}$

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	50	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	0.4	

Note:

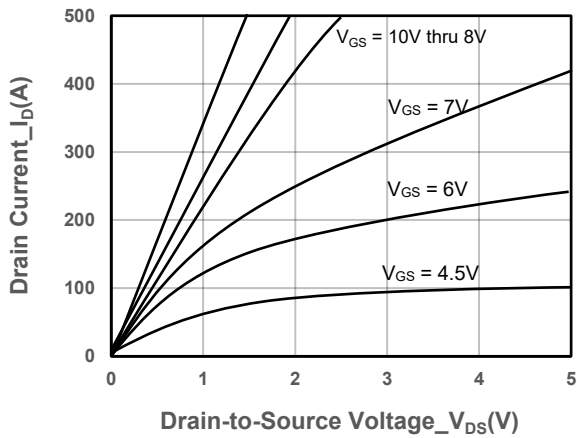
- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

**➤ Electrical Characteristics (T_A=25°C unless otherwise noted)**

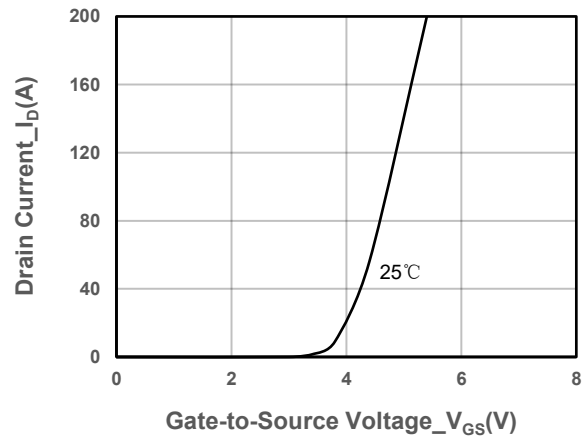
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	2.0	3.0	4.0	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		1.2	1.9	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±150	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 20A		0.75	1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		2.1		Ω
Input Capacitance	C _{ISS}	V _{DS} = 50V, V _{GS} = 0V, f = 1MHz		15000		pF
Output Capacitance	C _{OSS}			2500		
Reverse Transfer Capacitance	C _{RSS}			220		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 50V, I _D = 20A		205		nC
Gate to Source Charge	Q _{GS}			60		
Gate to Drain Charge	Q _{GD}			50		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 50V, I _D = 20A, R _G = 3.3Ω		40		ns
Rise Time	T _r			95		
Turn-off Delay Time	T _{D(OFF)}			110		
Fall Time	T _f			135		
Diode Recovery Time	T _{rr}	I _F =20A, di/dt=100A/us		100		ns
Diode Recovery Charge	Q _{rr}	I _F =20A, di/dt=100A/us		210		nC



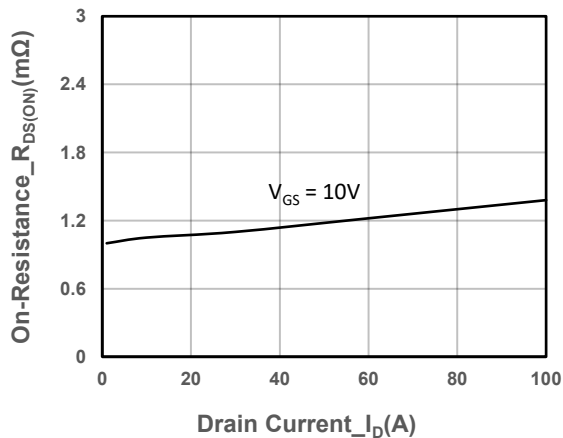
➤ **Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)**



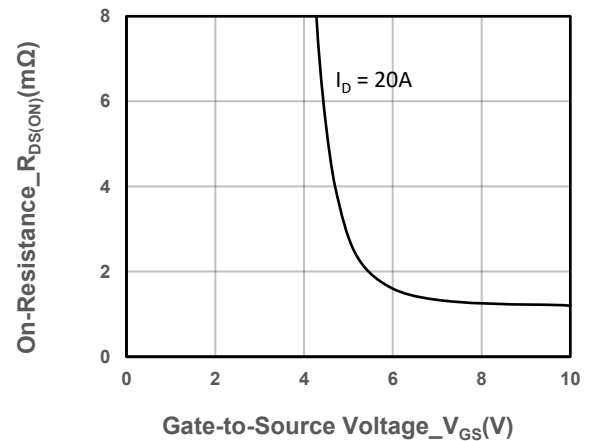
Output Characteristics



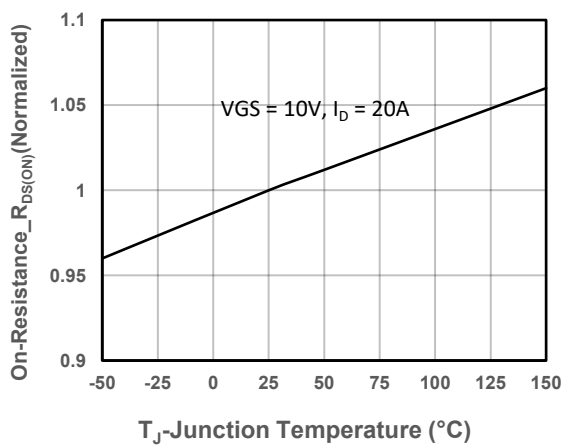
Transfer Characteristics



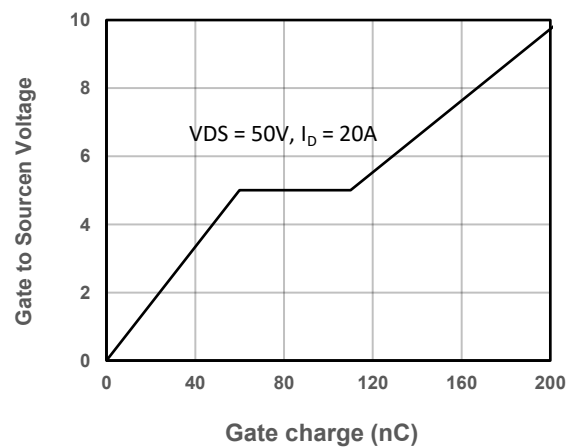
On-Resistance vs. Drain Current and Gate Voltg



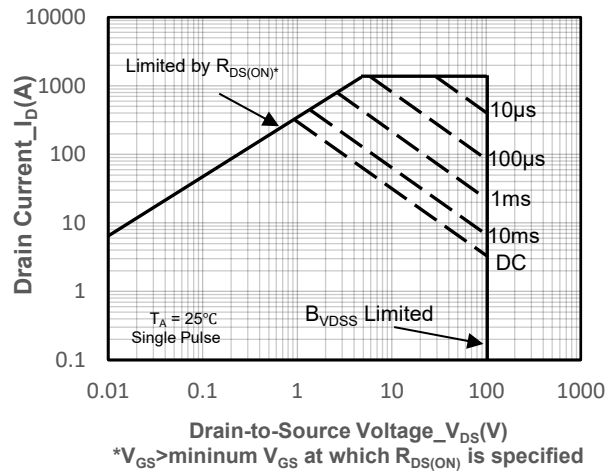
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



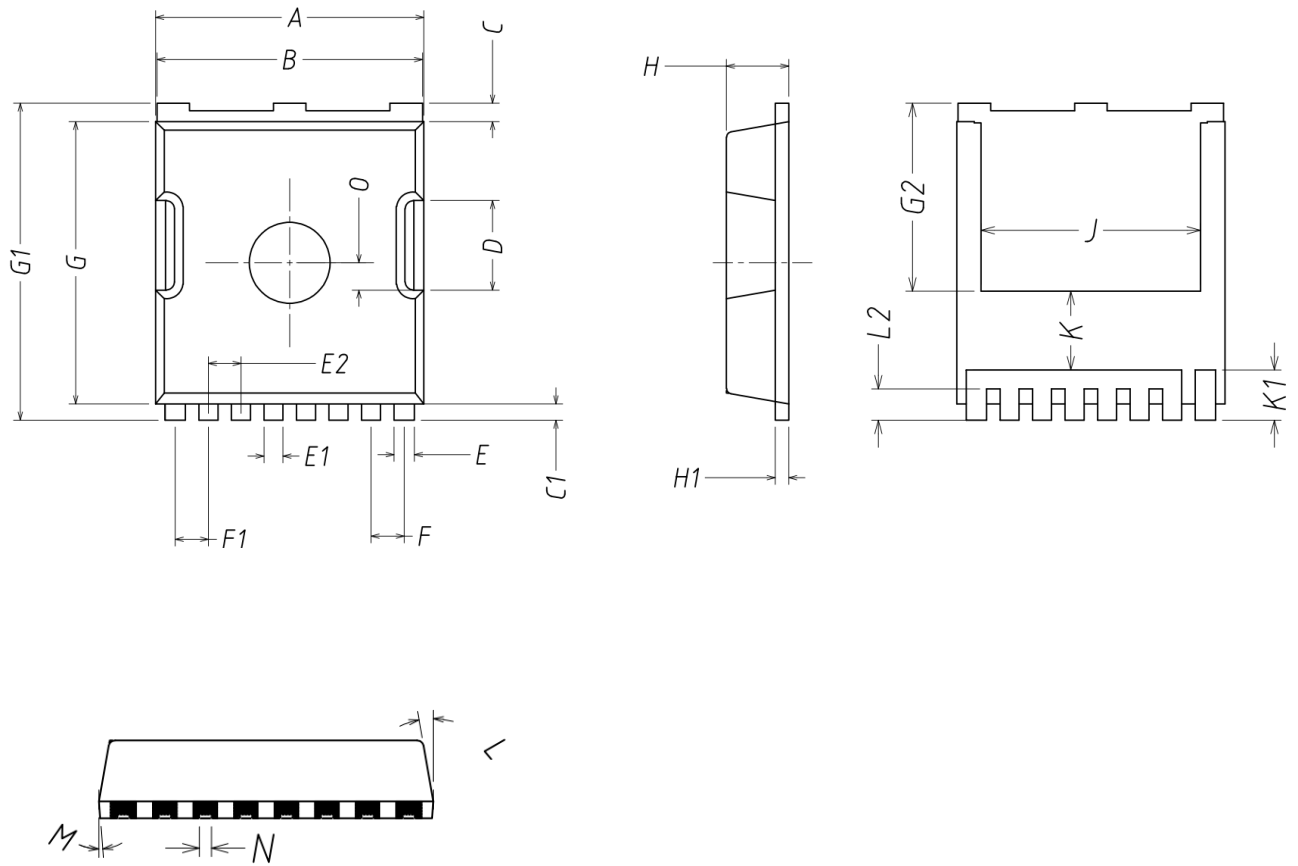
Gate-Source Voltage vs. Gate charge



Safe Operating Area vs. Junction-to-Ambient



➤ Package Information



COMMON DIMENSIONS (UNIT of MEASURE=MILLIMETER)															
SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	9.80	9.90	10.00	E1	0.60	0.70	0.80	G2	6.83	6.93	7.03	M	3.5°	4.5°	5.5°
B	9.70	9.80	9.90	E2	1.10	1.20	1.30	H	2.20	2.30	2.40	N	0.31	0.35	0.39
C	0.58	0.68	0.78	F	1.125	1.225	1.325	H1	0.45	0.50	0.55				
C1	0.45	0.60	0.75	F1	1.125	1.225	1.325	J	8.00	8.10	8.20				
D	3.15	3.30	3.45	G	9.40	10.40	11.40	K	2.80	2.90	3.00				
E	0.65	0.75	0.85	G1	11.53	11.68	11.83	L	9°	10°	11°				



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